

ELECTRICAL:

CONTACT RESISTANCE:

20 milliohms MAX at 1 amp. DC.

INSULATION RESISTANCE:

5,000 megohms MIN at 500VDC.

DIELECTRIC WITHSTANDING VOLTAGE:

800VAC/RMS at 60Hz for one minute.

VOLTAGE RATING:

800VAC/RMS at 60Hz.

CURRENT RATING:

1.0 amps. per contact.

MECHANICAL:

INSERTION FORCE: 230 grams MAX. per contact pair.

WITHDRAWAL FORCE: 15 grams MAX. per contact pair.

CONTACT RETENTION: 680 grams MAX. per contact pair.

DURABILITY:

200 mating/unmating cycles MIN. at flash gold over 0.76 micrometers MIN. of palladium/nickel

50 mating/unmating cycles MIN. at flash gold plating;

100 mating/unmating cycles MIN. at 0.38 micrometers MIN. gold plating;

200 mating/unmating cycles MIN. at 0.38 micrometers MIN. gold plating.

ENVIRONMENTAL:

OPERATING TEMPERATURE: -55°C to +105°C

HUMIDITY: per MIL-STD-1334A, method 1002.1, test condition B

THERMAL SHOCK: per MIL-STD-1334A, method 1003.1, test condition A

VIBRATION: per MIL-STD-1334A, method 2005.1, test condition II

MECHANICAL SHOCK: per MIL-STD-1334A, method 2004.1, test condition C

SALT SPRAY: 24 hours per MIL-STD-1334A, method 1001.1, test condition

MATERIAL:

INSULATOR:

glass-filled thermoplastic (PPS/NYLON-66/PBT), UL-94V-0 rated. color-white, for PCI connector

CONTACT:

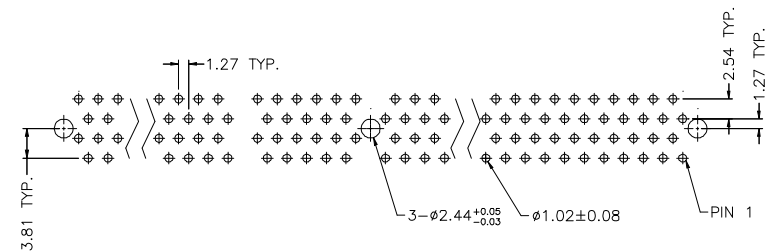
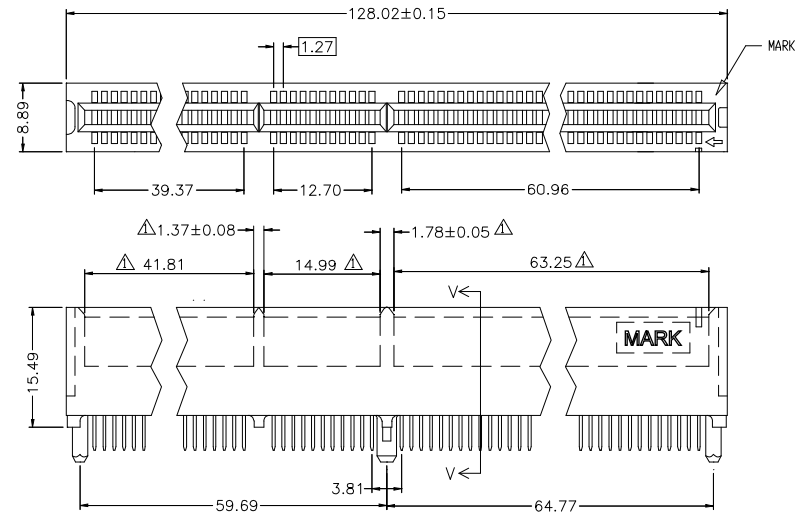
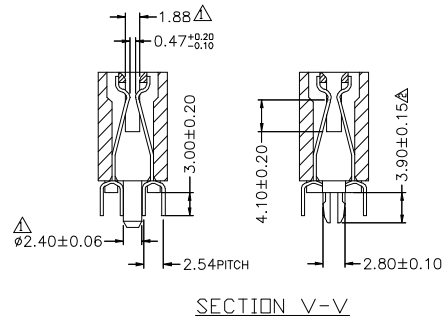
phosphor bronze, per ASTM-B103

Mating area - selective gold over 1.27 micrometers MIN. of nickel, or flash gold over 0.76 micrometers MIN. of nickel

Termination area - 2.54 micrometers MIN. of tin/lead over 1.27 micrometers MIN. of nickel

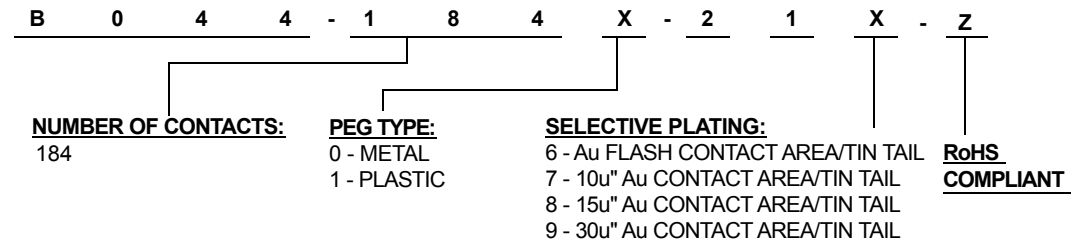
CLIPS (Boardlock):

stainless



P. C. B. HOLE LAYOUT

HOW TO ORDER:



Rev	Drawn	Checked	Approved	Date
0	S.E.	S.M.	S.M.M.A.	05/30/01
A	B.S.	S.M.	S.M.	07/07/08

SMP TECHNOLOGY, INC.

PCI Connector, 184 Positions, 5.0 Volt

TOL. DEC. .X +/- 0.25 .XX +/- 0.15 .XXX +/- 0.08 ANGLE +/- 0.50° UNIT: mm

P/N: B044-184X-21X-Z

Pg: 1